

## TABLE OF CONTENTS

<b>PREFACE .....</b>	<b>iii</b>
<b>Copper Deposition &amp; Patterning</b>	
Analysis of Copper Plating Baths – Suppressors and Levellers .....	1
<i>B. Newton and E. Kaiser</i>	
Effect of Thiourea on Electrodeposition of Copper from Acid Sulfate Solution .....	6
<i>V.S. Donepudi, R. Venkatachalamapathy, P.O. Ozemoyah, J. Prakash, And C.S. Johnson</i>	
Copper Electroplating onto Silicon Wafers Using High Frequency Acoustic Streaming .....	15
<i>I.I. Suni, C. Tiwari, A.A. Busnaina, H. Lin, H.V. Reynolds, and C. Neely</i>	
A Novel Contact Displacement Method for Cu Interconnect Fabrication .....	23
<i>Y-P. Lee, T-C. Hu, M-S. Tsai, M-S. Feng, and B-T. Dai</i>	
Role of Chemicals and Abrasive Particle Properties in Chemical-Mechanical Polishing of Copper and Tantalum .....	32
<i>Y. Li, A. Jindal, and S.V. Babu</i>	
Deposition of Copper MOCVD Using Hexafluoroacetylacetone Copper 1,5-Dimethylcyclooctane as a Precursor .....	47
<i>W. Lee, I-J. Byun, B. Seo, and J. Lee</i>	
Some Effects of Hydrogen on Cu(TMVS)(HFAC) Sourced CVD of Copper Films .....	54
<i>J. Hong, S. Srinivas, D. Yang, and T.S. Cale</i>	
Copper Dry Etching Using and Inductively Coupled O <sub>2</sub> Plasma and Hexafluoroacetylacetone .....	63
<i>W. Lee, H. Yang, and J. Lee</i>	
Effects of Plating Rack Design and Vibration Frequency on Displacement Uniformity During PCB Copper Plating under Mechanical Vibration .....	69
<i>R. Menini and H. Brown</i>	

Copper and Silver Inks for Ink Jet Printing .....	80
<i>T. Rivkin, C.J. Curtis, A. Miedaner, J. Alleman, D.L. Schulz, and D.S. Ginley</i>	

### **Electromigration & Reliability**

The Importance of Understanding of the Physics of Copper in Silicon for Development and Characterization of Copper Diffusion Barriers .....	90
<i>A.A. Istratov and E.R. Weber</i>	
Electromigration in Two-Level Cu Interconnections with a Low Dielectric Constant Inter-Level Insulator .....	112
<i>C.-K. Hu, L. Gignac, E. Liniger, R. Rosenberg, B. Agarwala, H.S. Rathore, and X. Chen</i>	
Electromigration Behavior of Cu Interconnects in Oxide Dielectrics .....	120
<i>B.N. Agarwala and H.S. Rathore</i>	
Electrochemical Study of the Electroless Deposition of Co(W,P) Barrier Layers for Cu Metallization .....	134
<i>N. Petrov and Y. Shacham-Diamand</i>	
Copper Contamination Issues in MOS Integrated Circuits .....	149
<i>K. Prasad, K.C. Tee, L. Chan, and A.K. See</i>	
An Optimized PECVD SiN Deposition for Borderless Contact Etch- Stop-Layer (ESL) of Sub-0.25 um Logic Devices .....	160
<i>H. Liu, J. Sudijono, C.W. Lim, W.Y. Leong, and K.H. Lam</i>	

### **Low-k Dielectrics**

Characterization of Polysilsequioxane Based Low-k Dielectrics .....	165
<i>M.J. Ko, M.S. Moon, D.S. Shin, J.W. Kang, and H.Y. Nam</i>	
Structural Properties of Porous Ultra Low-k Thin Films .....	175
<i>W. Chen, T.A. Deis, Y. Liu, J.N. Bremmer, E.K. Lin, D.W. Gidley, And W-A Chiou</i>	
Plasma Treatment of Hydrogen Silsesquioxane (HSQ) Based Ultra Low-k Films .....	184
<i>Q. Han, C. Waldorfried, I. Berry, W. Chen, E.S. Moyer, Y. Liu, and M.J. Spaulding</i>	

Characterization of Etch Processes for Low Dielectric Constant Materials .....	190
<i>G. Rajagopalan</i>	
H <sub>2</sub> O Vapor Assisted Plasma Chemistry for Photoresist and Polymer Removal over Low-k Materials .....	201
<i>R. Ruffin, C. Waldried, Q. Han, and I. Berry</i>	
Reducing Plasma Chemistry for Photoresist and Residue Removal over Low-k Materials .....	207
<i>C. Waldried, Q. Han, and J. Kuo</i>	
Effective Polymer and Etch Residue Removal Using Single-Wafer Processing .....	213
<i>D. Peters, M. Egbe, R. Rovito, J. Rieker, S. Fiener, T. Teo, T.-K. Seong, L.V. Nguyen, S-A. Henry, E. Gaulhofer, C. Haigermoser, and D. DeBear</i>	
<b>AUTHOR INDEX .....</b>	220
<b>SUBJECT INDEX .....</b>	223